



Click [here](#) for the 3D model.

### Dimensions

Chip Size	3040
L	7.6mm +/-0.4mm
W	10.2mm +/-0.4mm
T	2.5mm +/-0.20mm
S	4.2mm MIN
B	1.27mm +/-0.4mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	350

### General Information

Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	870 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	0.01 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	2000 VDC
Dielectric Withstanding Voltage	2400 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms